

L Number	Hits	Search Text	DB	Time stamp
-	5	Mizuocho-Masaki.in.	USPAT; US-FGPEU; EPC; JPO	2003/04/24 09:30
-	74	Fukushima-Yoshimasa.in.	USPAT; US-FGPEU; EPC; JPO	2003/04/24 09:30
-	20	Fukushima-Yoshimasa.in. and chamber	USPAT; US-FGPEU; EPC; JPO	2003/04/24 10:34
-	0	Inoue-Mitsuru.in.	USPAT; US-FGPEU; EPC; JPO	2003/04/24 09:31
-	5958	250/492.1.cols. 250/492.2.cols. 15/492.3.cols. 250/441.11.cols.	USPAT; US-FGPEU; EPC; JPO	2003/04/24 09:32
-	1634	250/492.1.cols. 250/492.2.cols. 15/492.3.cols. 250/441.11.cols.) and chamber	USPAT; US-FGPEU; EPC; JPO	2003/04/24 09:36
-	870	250/492.1.cols. 250/492.2.cols. 15/492.3.cols. 250/441.11.cols.) and table	USPAT; US-FGPEU; EPC; JPO	2003/04/24 09:33
-	111	250/492.1.cols. 250/492.2.cols. 250/492.3.cols. 250/441.11.cols.) and recess\$3 groove (same ring annul\$3))	USPAT; US-FGPEU; EPC; JPO	2003/04/24 09:34
-	20	250/492.1.cols. 250/492.2.cols. 250/492.3.cols. 250/441.11.cols.) and chamber) and (250/492.1.cols. 250/492.2.cols. 250/492.3.cols. 250/441.11.cols.) and table) and (250/492.1.cols. 250/492.2.cols. 250/492.3.cols. 250/441.11.cols.) and (recess\$3 groove (same ring annul\$3)))	USPAT; US-FGPEU; EPC; JPO	2003/04/24 09:36
-	1	Fukushima-Yoshimasa.in. and ((groove ring same recess\$3))	USPAT; US-FGPEU; EPC; JPO	2003/04/24 10:35
-	3	Fukushima-Yoshimasa.in. and ((groove ring same recess\$3 indentation cutout))	USPAT; US-FGPEU; EPC; JPO	2003/04/24 10:37
-	0	Fukushima-Yoshimasa.in. and ((annul\$3 same recess\$3))	USPAT; US-FGPEU; EPC; JPO	2003/04/24 10:37
-	201070	(groove ring annul\$3 (same recess\$3))	USPAT; US-FGPEU; EPC; JPO	2003/04/24 10:54
-	54221	(groove ring annul\$3 (same recess\$3)) and chamber	USPAT; US-FGPEU; EPC; JPO	2003/04/24 10:39
-	21044	(groove ring annul\$3 (same recess\$3)) and wafer substrate workpiece	USPAT; US-FGPEU; EPC; JPO	2003/04/24 10:39
-	6114	((groove ring annul\$3) same recess\$3)) and chamber) and (((groove ring annul\$3) same recess\$3)) and wafer substrate workpiece	USPAT; US-FGPEU; EPC; JPO	2003/04/24 10:40
-	1530	((groove ring annul\$3) same recess\$3)) and chamber) and (((groove ring annul\$3) same recess\$3)) and wafer substrate workpiece) and table	USPAT; US-FGPEU; EPC; JPO	2003/04/24 10:40
-	2572	((groove ring annul\$3) same recess\$3)) and chamber) and (((groove ring annul\$3) same recess\$3)) and wafer substrate workpiece) and vacuum	USPAT; US-FGPEU; EPC; JPO	2003/04/24 10:40
-	848	((groove ring annul\$3) same recess\$3)) and chamber) and (((groove ring annul\$3) same recess\$3)) and wafer substrate workpiece) and table and (((groove ring annul\$3) same recess\$3)) and chamber) and ((groove ring annul\$3) same recess\$3) and (wafer substrate workpiece)) and vacuum)	USPAT; US-FGPEU; EPC; JPO	2003/04/24 10:40

-	139	(((((groove ring annul\$3) same recess\$3)) and chamber) and (((groove ring annul\$3) same recess\$3)) and (wafer substrate workpiece))) and table and (((groove ring annul\$3) same recess\$3)) and chamber and ((groove ring annul\$3) same recess\$3) and (wafer substrate workpiece) and vacuum)) and table with (groove ring annul\$3)	USPAT; US-PGPUB; EPC; JPC	2003/04/24 10:43
-	54	((((groove ring annul\$3) same recess\$3)) and chamber) and (((groove ring annul\$3) same recess\$3) and (wafer substrate workpiece)) and table and (((groove ring annul\$3) same recess\$3)) and chamber and ((groove ring annul\$3) same recess\$3) and (wafer substrate workpiece) and vacuum)) and table with recess\$3)	USPAT; US-PGPUB; EPC; JPC	2003/04/24 10:43
-	32	((((groove ring annul\$3) same recess\$3)) and chamber) and (((groove ring annul\$3) same recess\$3) and (wafer substrate workpiece)) and table and (((groove ring annul\$3) same recess\$3)) and chamber and ((groove ring annul\$3) same recess\$3) and (wafer substrate workpiece) and vacuum)) and table with (groove ring annul\$3) and (((groove ring annul\$3) same recess\$3) and chamber) and ((groove ring annul\$3) same recess\$3) and (wafer substrate workpiece) and table) and (((groove ring annul\$3) same recess\$3) and chamber) and ((groove ring annul\$3) same recess\$3) and (wafer substrate workpiece) and vacuum)) and table with recess\$3)	USPAT; US-PGPUB; EPC; JPC	2003/04/24 10:43
-	702	((groove ring annul\$3) same recess\$3 and (lithography, photolithography))	USPAT; US-PGPUB; EPC; JPC	2003/04/24 10:55
-	259	((groove ring annul\$3) same recess\$3 and (lithography photolithography)) and chamber	USPAT; US-PGPUB; EPC; JPC	2003/04/24 10:55
-	177	((groove ring annul\$3) same recess\$3 and (lithography photolithography)) and table	USPAT; US-PGPUB; EPC; JPC	2003/04/24 10:58
-	90	((groove ring annul\$3) same recess\$3 and (lithography photolithography)) and chamber and ((groove ring annul\$3) same recess\$3) and (lithography photolithography) and table)	USPAT; US-PGPUB; EPC; JPC	2003/04/24 11:01
-	3177	recess\$3 with (wafer substrate workpiece)	USPAT; US-PGPUB; EPC; JPC	2003/04/24 11:02
-	7150	(recess\$3 with (wafer substrate workpiece) and recess\$3 same (groove ring annul\$3))	USPAT; US-PGPUB; EPC; JPC	2003/04/24 11:03
-	7150	(recess\$3 with (wafer substrate workpiece) and (recess\$3 with (wafer substrate workpiece)) and (recess\$3 same (groove ring annul\$3))	USPAT; US-PGPUB; EPC; JPC	2003/04/24 11:03
-	1801	((recess\$3 with (wafer substrate workpiece)) and (recess\$3 with (wafer substrate workpiece)) and (recess\$3 same (groove ring annul\$3)) and chamber	USPAT; US-PGPUB; EPC; JPC	2003/04/24 11:04
-	1182	((recess\$3 with (wafer substrate workpiece)) and (recess\$3 with (wafer substrate workpiece)) and (recess\$3 same (groove ring annul\$3)) and table	USPAT; US-PGPUB; EPC; JPC	2003/04/24 11:04

-	463	((recess\$3 with (wafer substrate workpiece) and ((recess\$3 with (wafer substrate workpiece) and (recess\$3 same (groove ring annul\$3))) and chamber) and ((recess\$3 with (wafer substrate workpiece) and ((recess\$3 with wafer substrate workpiece) and recess\$3 same (groove ring annul\$3))) and table))	USPAT; US-PGPUB; EPO; JFC	2003/04/24 11:04
-	67	((recess\$3 with (wafer substrate workpiece) and ((recess\$3 with wafer substrate workpiece) and recess\$3 same (groove ring annul\$3))) and chamber) and ((recess\$3 with (wafer substrate workpiece) and ((recess\$3 with wafer substrate workpiece) and recess\$3 same (groove ring annul\$3))) and table)) and lift grip\$2	USPAT; US-PGPUB; EPO; JFC	2003/04/24 11:29
-	21780	(vacuum evacuat\$3) with (ring annul\$3)	USPAT; US-PGPUB; EPO; JFC	2003/04/24 11:35
-	450	((vacuum evacuat\$3) with (ring annul\$3)) same table	USPAT; US-PGPUB; EPO; JFC	2003/04/24 11:36
-	1395	((vacuum evacuat\$3) with (ring annul\$3)) same recess\$3	USPAT; US-PGPUB; EPO; JFC	2003/04/24 11:36
-	29	((vacuum evacuat\$3) with (ring annul\$3)) same table and ((vacuum evacuat\$3) with (ring annul\$3) same recess\$3)	USPAT; US-PGPUB; EPO; JFC	2003/04/24 11:37
-	179	73 000.pcls.	USPAT; US-PGPUB; EPO; JFC	2003/04/24 12:39
-	112	73 000.pcls. and table	USPAT; US-PGPUB; EPO; JFC	2003/04/24 12:30
-	42	73 000.pcls. and (groove annul\$3 recess\$3)	USPAT; US-PGPUB; EPO; JFC	2003/04/24 12:34
-	10078	43 000.pcls. and table	USPAT; US-PGPUB; EPO; JFC	2003/04/24 12:50
-	484	((438 000.pcls. and table) and ((vacuum evacuat\$3) same (ring annul\$3 groove)))	USPAT; US-PGPUB; EPO; JFC	2003/04/24 12:51
-	484	((438 000.pcls. and table) and ((vacuum evacuat\$3) same (ring annul\$3 groove))) and table	USPAT; US-PGPUB; EPO; JFC	2003/04/24 12:51
-	121	((438 000.pcls. and table) and ((vacuum evacuat\$3) same (ring annul\$3 groove))) and recess\$3	USPAT; US-PGPUB; EPO; JFC	2003/04/24 12:51
-	121	((438 000.pcls. and table) and ((vacuum evacuat\$3) same (ring annul\$3 groove))) and table and ((438 000.pcls. and table) and ((vacuum evacuat\$3) same (ring annul\$3 groove))) and recess\$3	USPAT; US-PGPUB; EPO; JFC	2003/04/24 12:53
-	446149	(hitachi cannon).as.	USPAT; US-PGPUB; EPO; JFC	2003/04/24 12:53
-	19566	((hitachi cannon).as.) and chamber	USPAT; US-PGPUB; EPO; JFC	2003/04/24 12:53
-	66	((hitachi cannon).as.) and chamber) and (table with (groove annulus ring))	USPAT; US-PGPUB; EPO; JFC	2003/04/24 12:54
-	0	lithography same table same groove same recess\$3	USPAT; US-PGPUB; EPO; JFC	2003/04/24 13:21